

Abstract of the Invention

5       An improved cooling system provides cooling  
away from the surface of electrical and electronic  
components with very low parasitic power consumption  
and very high heat transfer rates. The component to  
be cooled is in thermal contact with a cold plate  
evaporator device. Refrigerant is circulated by a  
liquid refrigerant pump to the cold plate evaporator  
10 device, and the liquid refrigerant is at least  
partially evaporated by the heat generated by the  
component. The vapor is condensed by a conventional  
condenser coil and the condensed liquid along with  
any unevaporated liquid is returned to the pump. The  
15 system operates nearly isothermally in both  
evaporation and condensation.